

Form Type	Distribute	Version	2.0 Ref		Ref	IPC 1		2A	A Sectionals		Manufacturin Info/ Material Info	Subsectiona	ls D, A	
			l		S	upplier li	nformatio	n	l					
Company Name	TE Connectivi	ty Request Document I	D			Contact Name		Chan, Nelson		Cont		Global Account Manager, HKG SELL DIR-EMS		
Company Unique ID	TE Connectiv	ty Response [Response Date		2018-03-30		Contact Email		nelson.chan@te.com					
Contact Phone I	Number	+852-2738-8	3751											
						Legal St	atement							
Supplier Acceptance	true													
egal Statement	!													
The information provided	provided in this	document is base ecifications or exi	d upo	n reasonab	le inqui	ry of our s	suppliers.	This inf	ormation is	subje	ct to change.	This information	does not in a	any
ray modify existi	ng purchase sp	ecilications of ext	Stirry	contractual	OI OIIIE		duct	betwe	en il con	IICCLIVI	ty (Of its affilia	ted companies) a	ind its casto	incia
Manufacturer	1-1624117-6	Amount		11.7		Version	uucı	_		Ident	tity			
tem number	1 1024117 0	Amount	Aillouit		11.7		ACIZIOII		iden		iity			
Manufacturer tem Name	BMB-B 0805 600R	Weight Uom		mg		Mfr Site				Auth	ority			
ate		UOM		Each										
URoHS-0508	Product(s) meets EU RoHS requirement without any exemptions													
ChinaRoHS- 508	Product(s) is e	eligible for markin	g with	the e code	under	China's M	leasures	or Adm	inistration (of the o	control of pollu	tion by Electroni	Information	n
UREACH-0117	REACH Cand	idate Substances	of Ve	ry High Co	ncern A	RE NOT	Containe	d in the	Product Al	ove th	ne Limits per tl	ne Definition with	in REACH	
Complex Article Description	REACH Cand	idate Substances	of Ve	ery High Co	ncern a	ccording	to Once a	n Article	e Always a	n Artic	le are Not Yet	Reviewed		
					Man	ufacturin	g Inform	ation						
-STD-020 MSL Rating		Max Total a Wave Time				Ramp Rate			Wav Addi		e tional Info			
Classification Temp	Max Wave Solder Time)	20.0		Ramp Down Rate			Psi F Refle		Rating ow			
Max Time Within 5		Psl Rating Wave				Package Designator			Size			0.0		
Time Above 217		Reflow Additional I		ifo		Preheat I Temp				Terminal Base Alloy		Not Applicable		
Preheat Ouration		bulk Solder Termination			able Nbr or R		Reflow		Term Platir			Not Applicable	licable	
Preheat Min Temp		Nbr of Instances			Component Temp Spike			Shape		ре	Not Applicable			
•	•	•			F	Product E	Disclosur	е		•				
Sub- tem/Material/ Substance	Level	Name	ne Subs Cate		Substa CAS	ance	Substar Concen		Quantity		Mass per Un	it UOM	Exempt	tion
	1	Ceramic body							1.0		10.179	mg		
	2	Nickel oxide (NiO)	Supp	olier	1313-9	1313-99-1		7.0		1.0		mg		
Substance	2	Iron oxide (Fe2O3)	Supplier		1309-37-1		60.0		1.0		6.1074	mg		
Substance	2	Zinc oxide (ZnO)	Supp	Supplier		1314-13-2		25.0			2.54475	mg		
Substance	2	Copper oxide (CuO)	Supplier		1317-38-0		8.0		1.0		0.81432	mg		
Material	1	Terminal(Paste							1.0		1.034	mg		
Substance	2	Silver	Supp	Supplier		7440-22-4		100.0		1.0		mg		
	1	Sn Plating							1.0		1.034 0.266	mg		
	2	Tin	Supp	lier	7440-31-5		100.0		1.0		0.266	mg		
/laterial	1	Ni Plating							1.0		0.089	mg		
Substance	2	Nickel	Nick	el	7440-0)2-0	100.0		1.0		0.089	mg		
/laterial	1	Cu Plating										mg		
viateriai	·		_								0.132			